

AMENDMENT OF THE SPECIFICATION

Page 1, before the first paragraph, insert the following centered heading:

BACKGROUND

Page 1, before the last paragraph, insert the following centered heading:

SUMMARY

Page 2, delete the first paragraph in its entirety.

Page 2, amend the fourth paragraph to read:

According to ~~claim 1~~ one method, the adhesive layer is dissolved and the individual chips lifted off the carrier substrate with a suction head. They are then preferably deposited in a special tray for further processing. In this method the chips lie in the special trays with their backsides upward. Alternatively, the chips can of course also be processed immediately, for example immediately mounted on a smart card or smart card foil.

Page 2, amend the fifth paragraph to read:

~~Claim 2 provides according to the invention a further method step According to another method, an additional step is included~~ wherein the individual chips still located on the carrier substrate are glued on the backside with a continuous carrier film by means of a second adhesive layer after sawing. The first adhesive layer is then dissolved with a method which retains the second adhesive layer. The chips can then be lifted off the carrier substrate together, joined by the carrier film. It is

then possible to remove the individual chips from the carrier film by dissolving the second adhesive layer. Removal can also be done with the aid of a suction head or the like here. In this method the active front side of the chip is then on top.

Page 2, the last paragraph is amended to read:

According to yet another method, ~~claim 3~~ it is provided according to the invention that said carrier film is glued on directly after thinning of the wafer and the wafer saw-diced into individual chips only then. The film remains on the individual chip upon incorporation of the smart card; the chip is thus reinforced by the carrier film and can also be handled by conventional methods and tools. The use of suitable, e.g. viscoplastic, materials for the carrier foil permits the latter to be kept relatively thin while ensuring sufficient stability of the chip-foil compound.

Page 3, amend the third paragraph to read:

Alternatively, it is fundamentally also possible for the carrier substrate itself to be dissolved together with the adhesive layer between wafer and carrier substrate, or instead of said adhesive layer. It goes without saying that a method is chosen for this purpose which does not attack the second adhesive layer ~~in the methods according to claim 2 or 3.~~

Page 4, before the sixth paragraph, insert the following centered heading:

#### BRIEF DESCRIPTION OF THE DRAWINGS

Page 5, amend the third paragraph to read:

Figs. 40/41 10a, 10b, 11a and 11b show production of a smart card by laminating two card foils together,

Page 5, amend the fourth paragraph to read:

Figs. 42/43 12a, 12b, 12c, 13a, 13b and 13c show variants of a smart card with a thinned chip applied to the surface to terminal areas already present.

Page 5, after the fourth paragraph, insert the following centered heading:

#### DETAILED DESCRIPTION OF VARIOUS EMBODIMENTS